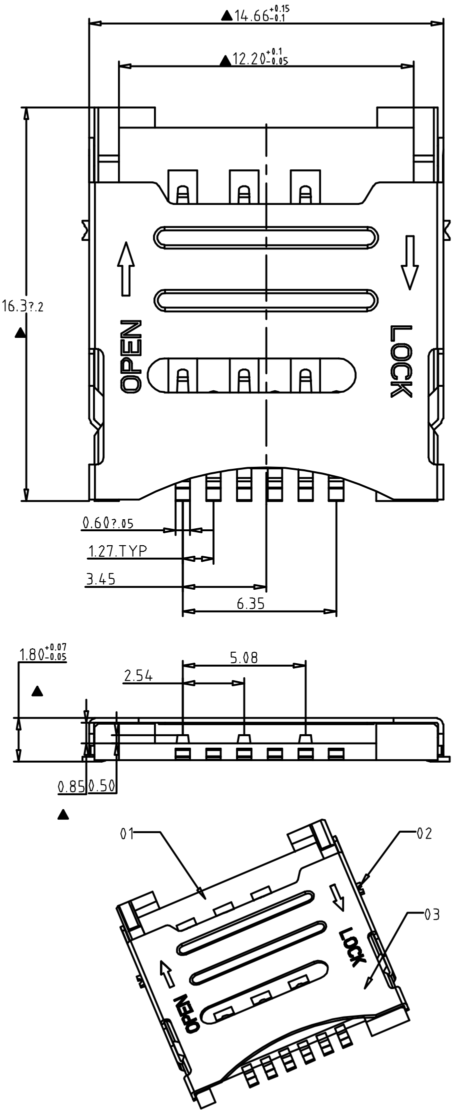
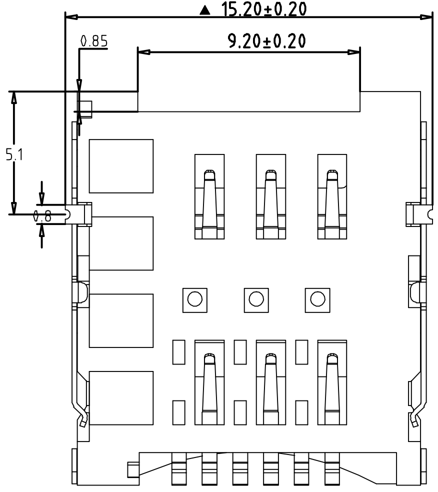
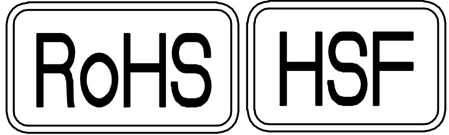






一、材质和镀涂:

1、胶芯: LCP，UL 94 V - 0,黑色

?、端子: 磷铜C5210-H，T=0.15，镍底镀金

?、外壳: 不锈钢 SUS304 T=0.2

二、技术参数:

接触电阻: 100mΩ Max

绝缘阻抗: 1000MΩ Min(500DC)

额定电流: 每个接触件1A Max

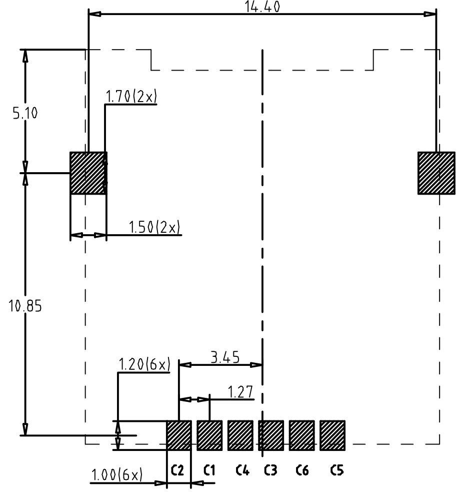
额定电压: 30V Max(DC)

耐　　压: 500V r.m.s/min

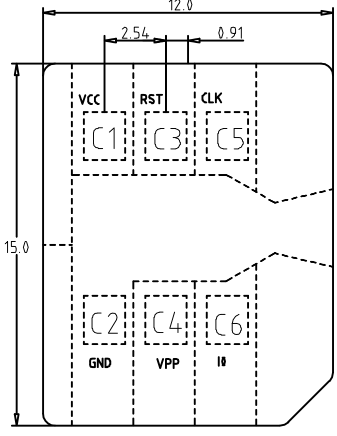
使用温度: -40℃~85℃

湿　　度: 90%~95%

寿　　命: >3000次



PCB LAYOUT



MICRO SIM

PIN NO.	NAME	PIN NO.	NAME
C1	VCC	C4	VPP
C2	GND	C5	CLK
C3	RST	C6	IO

東莞市訊普電子科技有限公司

E	PRODUCT SPEC. MICRO SIM
TITLE:	Mini SIM + H1.8
PART NO.	SMC-216
FILE NAME.	
SCALE 1:1	UNIT:mm A4 SHEET:1 of 1

工程变更通知单号 ECN(DCN) NO.	版次 REV	日期 DATE	说明 DESCRIPTION	改变 CHANGE	承认 APPRO.
	B	17'/10/27	修改实物与图纸相符	赵文博	
	A	10'/08/20	NEW RELEASE		

General	Angle			
X±0.50	X°±2°	设计 DESIGN	Nicolas	10'/08/20
.X±0.30	.X°±1°			
.XX±0.20	.XX°±0.5°	校阅 CHECK	Nicolas	10'/08/20
GENERAL TOLERANCE UNLESS OTHERWISE NOTED		承认 APPRO.		

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EN/ISO5961 Determination of total lead & cadmium content (总铅和总镉含量测定)
EN1122 Determination of total lead & cadmium content (总铅和总镉含量测定)
EN13346 Determination of heavy metals content (重金属含量测定)
EPA3052 Determination of total lead & cadmium content (总铅和总镉含量测定)

3. FEATURE & DIMENSIONS （特征及尺寸）

3.1. PRODUCT DIMENSION （产品尺寸）

These connectors shall have the dimensions as shown in customer drawing。
本产品的相关尺寸参见客户图面。

3.2. PCB/PANEL LAYOUT （印刷电路板布局）

The recommended PCB layout is shown in customer drawing。
本产品适用的PCB layout参见客户图面。

3.3. MATERIAL （材料）

The harmful material can follow the requirement of RoHS.
本产品使用的材料符合 RoHS 指令要求。

3.4. MECHANICAL & ELECTRICAL CHARACTERISTIC （机械及电气特性）

The connector shall have the mechanical and electrical performance as described in table I：
本产品的机械及电气特性见附表 I 。

3.5. PACKAGING （包装）

Products shall be packaged according to requirements specified in purchase order for safe delivery. Products required tray or carrier tape should meet the proper specification per purchase order. Connector container and the packaging specification is shown in customer drawing。
产品包装可依客户指定要求。本产品采用卷带包装，具体规格见客户图面。

3.6. MARKING（标识）

Manufacturer’s name, industry recognized logo, or customer approved marks。
标示制造商的名称，或客户认可的相关标志。

3.7.TRANSPORTATION （运输）

Any vehicle can be adopted for the transportation, but moisture-proof and no mechanical damage.
可采用任何运输工具运输，勿淋湿及机械性损伤。

4.2.1.1. Preheat（预热）

Increase in temperature not to exceed **4**℃per second. Final preheat temperature will be within **125**℃of solder temperature. 温度增加不超过**4**℃ /秒，最终预热温度不超过**125**℃.

4.2.1.2. Soldering（焊接）

Device leads will be exposed to solder wave at **250**℃for a maximum of 5 seconds. 设备中的引导焊接温度最高**250**℃不超过5秒.

4.2.1.3. Cool Down（冷却）

Cool down in ambient air at approximately **20**℃**to 25**℃. 冷却到周围环境温度**20**℃**~ 25**℃.

4.2.2. INFRARED REFLOW （红外线回流焊）

Three cycles. Each cycle consisting of three consecutive phased. 三个周期，每个周期包括三个连续的阶段完成；

4.2.2.1. Preheat（预热）

Increase in temperature not to exceed 4℃ per second. 温度增加不超过**4**℃ /秒，

4.2.2.2. Soldering（焊接）

Maximum allowable time above reflow temperature of **183** ℃ is **90** seconds. Maximum temperature in this interval is 260℃, not to exceed 10 seconds. 回流焊温度**183**℃以上的时最长不超过 90秒. 最高温度260℃时间不超过10秒.

4.2.2.3. Cool Down（冷却）

Cool down shall not exceed 6℃ per second. 冷却速度不超过6℃/秒. **Note:**（注）Device temperature measurements are referenced from the top-center of the package outer surface. 设备温度量测时以从顶部中间位置测量为准；

4.3. CLEANING （清洗）

Connectors resist to cleaning process. Aqueous Cleaning: Three cycles; each cycle consisting of a maximum of one minute exposure to 54℃ to 66℃ demineralized tap water at a maximum pressure of 30 psi; followed by air drying for 60℃to 90 seconds at 93℃ to 121℃.

产品本身可以承受清洗制程. 水洗：包含三个循环；每个循环包括以下：以最大压力30帕，温度 54℃~ 66℃，去除矿物质的水，用水龙头冲洗最多一分钟，然后用温度 93℃~121℃的空气吹60到90秒；

Products qualification test sequence as shown in **Table II.**
产品品质测试顺序见附表二**.**

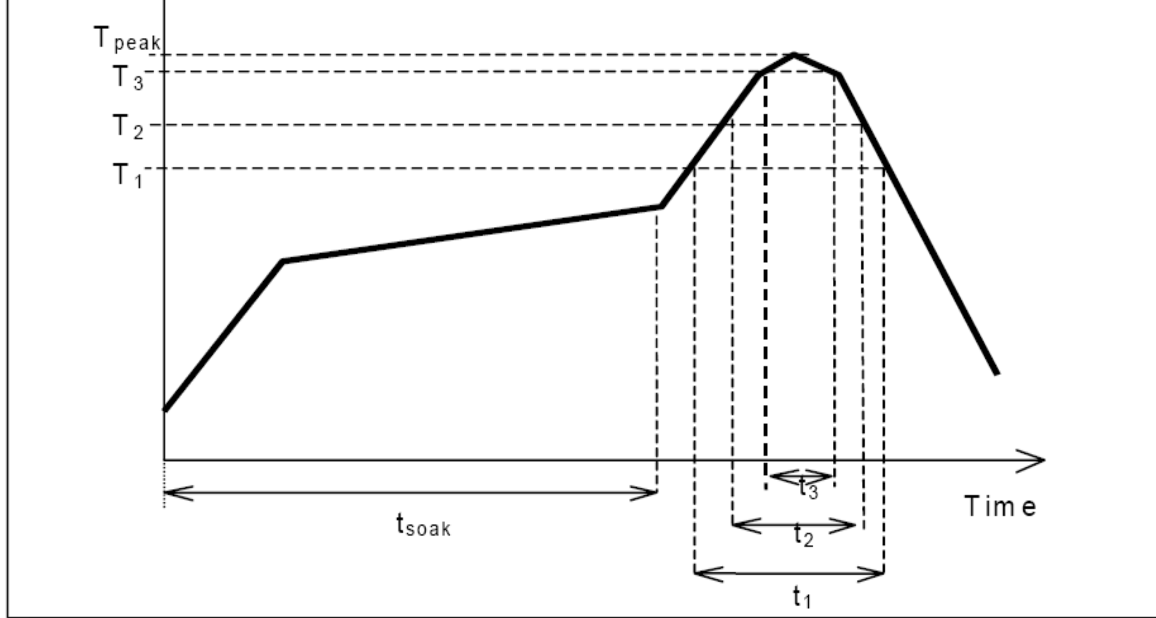
6. QUALITY ASSURANCE PROVISIONS （品质保证）

Company is responsible for the quality of the part as it is delivered to customer. Failing lots will be return or other supplier corrective action.
本公司对出给客户的所有产品品质负责，不良批次的产品退回或由供应商做矫正；

		contacts and ground in the mated connector. MIL-STD-202, Method 302, Condition B (500 V DC±10%). 测试产品端子间以及端子与接地间的电阻，适用：MIL-STD-202，方法302，条件B (500V DC±10%) 。
4. Dielectric Strength 耐电压	Connector must withstand test potential of 500 V AC for 1 minute. Current leakage must be 1.0 mA max.. 样品必须承受测试电 500V AC，时间一分钟，漏电流不大于1.0 mA.	Measure by applying test potential between the adjacent contacts, and between the contacts and ground in the mated connector. MIL-STD-202, Method 301. 测试产品端子间以及端子与接地间的电压，适用：MIL-STD-202 ，方法 301 。
5. Durability (Repeated Mating/Unmating) 耐久力	Contact Resistance: **100** mΩ Max. after testing 完成插拔测试后接触阻抗不大于100 mΩ	Mate and unmate connector for 5000 cycle . 同配合产品进行5000次插拔。
6. Temperature rise 温度急变	30° C Max. 不高于30° C	Carry rated current load.0.3A per contact.（UL498）每根端子负载0.3A 电流。（UL498）
7.Vibration Sinusoidal Low Frequency 低频正弦振动	No electrical discontinuity greater then 1 μsec (s) shall occur. Contact resistance:**100** mΩmax. 不允许出现超过1 μsec (s) 的瞬间断开，接触阻抗：100 mΩ最大；	Subject mated connector to 10-55-10 Hz traversed in 1 minute at 1.5 mm amplitude 2 hours each of 3 mutually perpendicular plane, 10 mA applied MIL-STD-202, Method 201. 对测试样品，在频率变化每分钟从10-55-10 Hz，振幅 1.5 mm 条件下，在互相垂直的三个面上，每个面2 小时下测量，电流 10 mA ；适用：MIL-STD-202 ，方法 201。
8. Shock 冲击	No electrical discontinuity greater than 1 μsec. shall occur. No damage to product. 不允许出现超过1 μsec (s) 的瞬间断开，产品无损坏；	Applying an appropriate holder is allowed in vibration test and shock test. MIL-STD-202, Method 213,490m/s^2, 3 axes. 使用合适的固定方式，适用方法. MIL-STD -202，方法213，加速度490m/s2，三个轴上均做测试。

	接触阻抗：100 mΩ最大；耐电压测试OK，绝缘阻抗100MΩ最小；	
11.Solderability 可焊性	Appearance of the specimen shall be inspected after the test with the assistance of a magnifier capable of giving a magnification of 10 X for any damage such as pinholes, void or rough surface. 样品在测试完成后，用放大倍数为10 倍的显微镜，检查外观损坏如：小孔，空焊，外观粗糙度；	Soldering time: 3 to 5 Seconds Temperature: 255±5°C. 焊接时间：3~5 秒，温度：255±5°C。
12.Resistance to soldering heat 耐焊接热	No damage 产品无损坏	Leave subject product in the 255±5°C chamber for 2 minutes. 产品置于255±5°C 烘箱内2 分钟。
13. Salt Spray 盐雾	Contact Resistance (Low Level) (Final) **100** mΩmax. 接触阻抗(末态) 100 mΩmax.	5±1% salt concentration 24±4 hours 35±2°C MIL-STD-202, Method 101 Condition B. 盐水浓度（重量比）5±1%，镀金区域时间24小时，镀锡区域时间8小时。温度35±2°C；MIL-STD-202，方法101 ，条件B。
14.High temperature 高温	Contact resistance: **100** mΩ max. 接触阻抗100 mΩmax.	Subject product to 85±2°C for 96 hours continuously. MIL-STD-202, Method 108. 产品置于85 ±2°C 连续96 小时，适用MIL-STD-202，方法108。

6. Temperature rise 温度急变		**3**							
7. Vibration Sinusoidal Low Frequency 低频正弦振动			**3**						
8. Shock 冲击				**3**					
9. Thermal shock 热冲击					**5**				
10. Humidity 恒温恒湿					**7**				
11. Solderability 可焊性						**2**			
12. Resistance to soldering heat 耐焊接热							**2**		
13. Salt Spray 盐雾								**5**	
14. High temperature 高温									**5**



This profile is the minimum requirement for evaluating soldering heat resistance of components. Heat transfer method used for reflow soldering is hot air convection. The actual air temperatures used to achieve the specified profile is higher and largely dependent on the reflow equipment.

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